

**8.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER**

**Product Summary** (@T<sub>A</sub> = +25°C)

<b>V<sub>RRM</sub> (V)</b>	<b>I<sub>o</sub> (A)</b>	<b>V<sub>F</sub> (V)</b>	<b>I<sub>R</sub> (μA)</b>
1000	8.0	1.00	5

**Description and Applications**

General purpose use in AC-to-DC bridge full wave rectification for Fast Charging, Switching Power Supply, USB PD, Adapter and 3-in-1 DTV Power Board, etc.

**Features and Benefits**

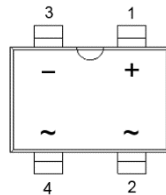
- Glass Passivated Die Construction
- Miniature Surface Mount Package Saves Space on PC Boards
- High Current Capability
- High Forward Current Capability up to 8.0A
- High Heat Dissipation Capability
- Low Profile Package
- Low Forward Voltage Drop
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

**Mechanical Data**

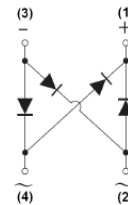
- Case: HBS
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: As Marked on Body
- Weight: 0.389grams (Approximate)



Top View



Pin Diagram



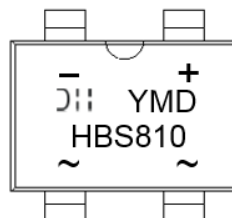
Internal Schematic

**Ordering Information** (Note 4)

Part Number	Compliance	Case	Packaging
HBS810-13	Commercial	HBS	2,500/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**



HBS810 = Product Type Marking Code  
 ⌋⌋⌋ = Manufacturers' Code Marking  
 YMD = Date Code Marking  
 Y = Last Digit of Year (ex: 0 = 2020)  
 M = See Month/Code Table Below  
 D = Day 1 to 9 = 1 to 9; Day 10 to 31 = A to V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	1,000	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	700	V
Average Rectified Output Current (Note 5) @ T <sub>A</sub> = +25°C	I <sub>O</sub>	8.0	A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	200	A
Non-Repetitive Peak Forward Surge Current, 1.0ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	290	A
I <sup>2</sup> t Rating for Fusing (1ms < t < 8.3ms)	I <sup>2</sup> t	166	A <sup>2</sup> S

### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element)	R <sub>θJA</sub>	70	°C/W
Typical Thermal Resistance, Junction to Lead (Per Element)	R <sub>θJL</sub>	14	°C/W
Typical Thermal Resistance, Junction to Case (Per Element)	R <sub>θJC</sub>	11	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	1,000	—	—	V	I <sub>R</sub> = 10μA
Forward Voltage (Per Element)	V <sub>F</sub>	—	0.82 0.89 0.94	0.87 0.94 1.00	V	I <sub>F</sub> = 1A, T <sub>A</sub> = +25°C I <sub>F</sub> = 4A, T <sub>A</sub> = +25°C I <sub>F</sub> = 8A, T <sub>A</sub> = +25°C
Leakage Current (Note 6) (Per Element)	I <sub>R</sub>	—	0.15 20	5 100	μA	V <sub>R</sub> = 1,000V, T <sub>A</sub> = +25°C V <sub>R</sub> = 1,000V, T <sub>A</sub> = +125°C
Total Capacitance (Per Element)	C <sub>T</sub>	—	63	—	pF	V <sub>R</sub> = 4V, f = 1.0MHz

Notes: 5. Device mounted on 15mmx12mmx1.6mm AL Pad attached on 100mmx75mmx27mm Fin heatsink. Thermal resistance test performed in accordance with JESD-51.  
6. Short duration pulse test used to minimize self-heating effect.

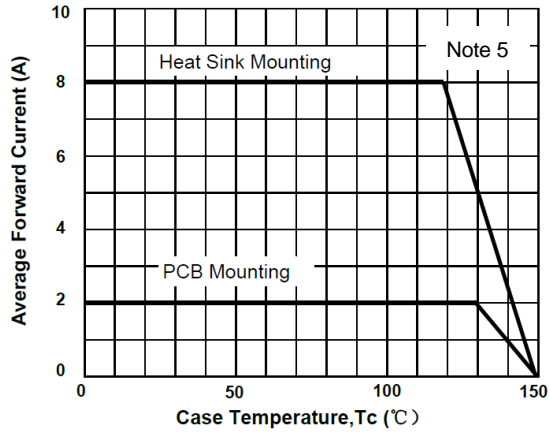


Figure 1. Forward Current Derating

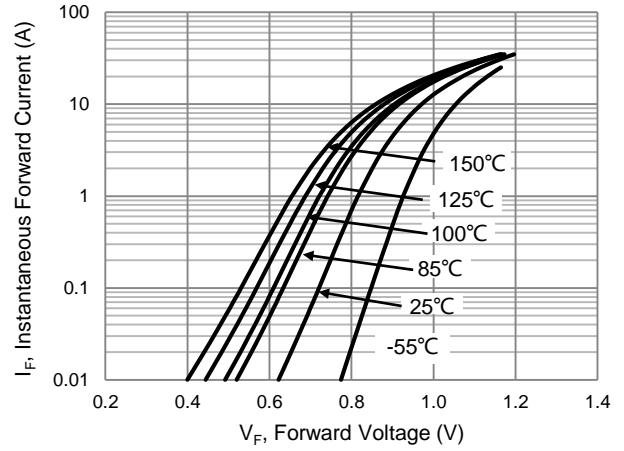


Figure 2. Typical Forward Characteristics

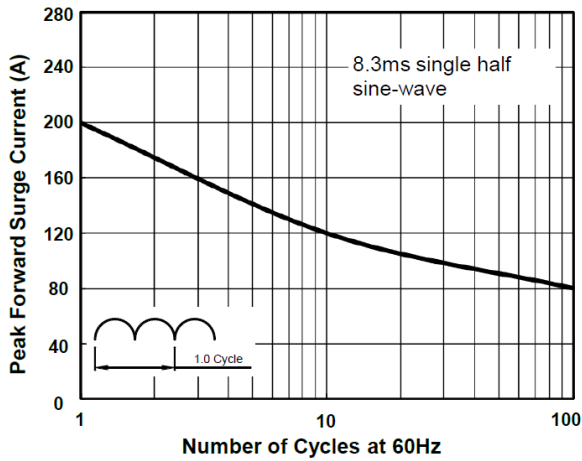


Figure 3. Maximum Non-Repetitive Forward Surge Current

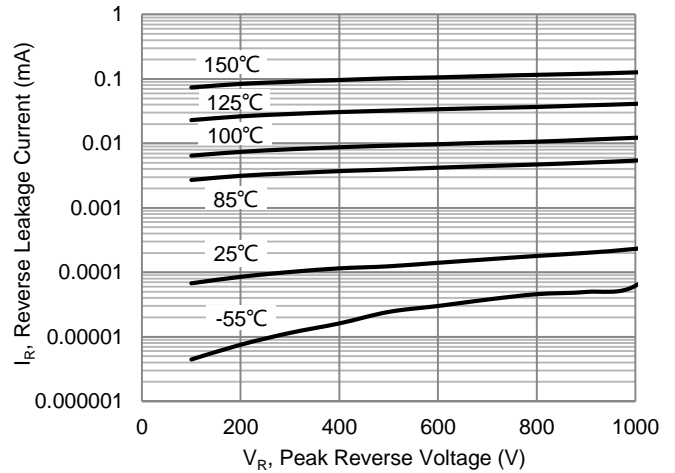


Figure 4. Typical Reverse Characteristics

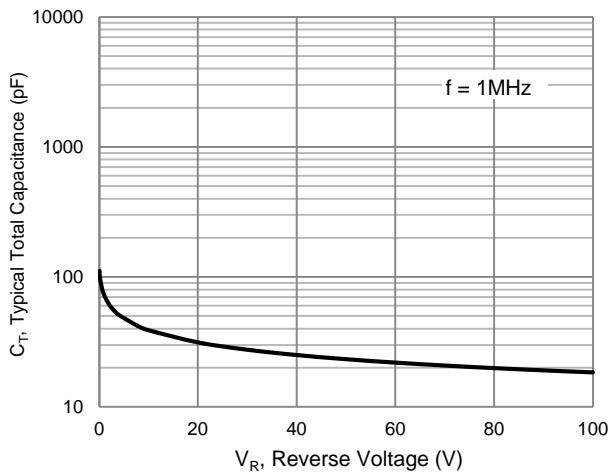
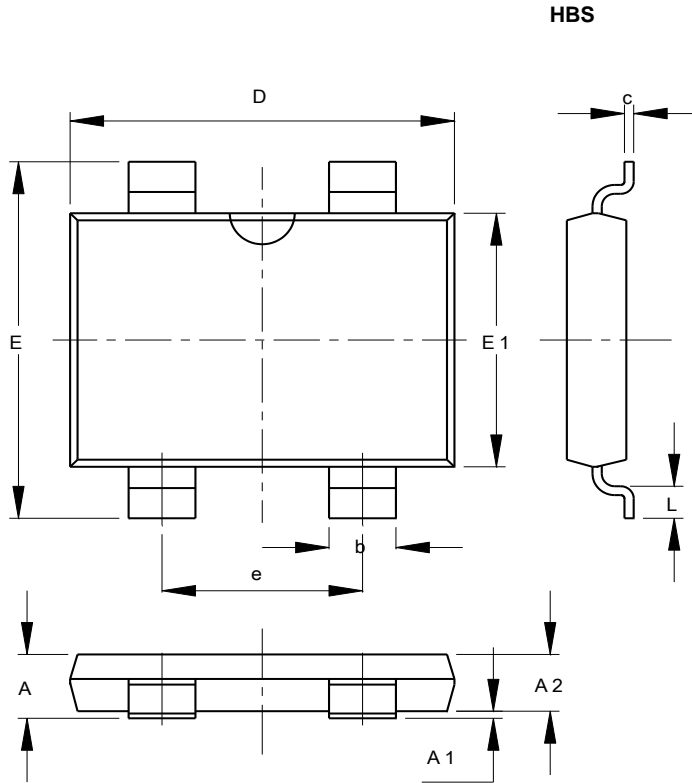


Figure 5. Typical Total Capacitance

**Package Outline Dimensions**

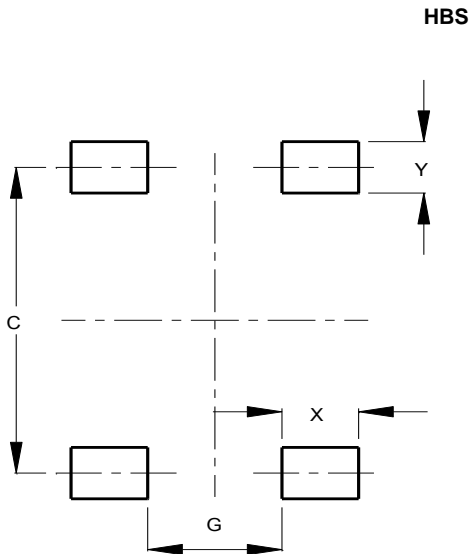
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



HBS			
Dim	Min	Max	Typ
A	1.45	1.80	--
A1	0.00	0.20	--
A2	1.45	1.65	--
b	1.70	1.90	--
c	0.15	0.35	--
D	10.05	10.35	--
E	9.75	10.05	--
E1	6.85	7.15	--
e	5.25	5.60	--
L	0.45	0.95	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	8.92
G	3.50
X	2.00
Y	1.50

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